



INTERNATIONAL MICROELECTRONICS AND PACKAGING SOCIETY

Bringing Together The Entire Microelectronics Supply Chain!



Industry
Systems & Applications
Design
Materials & Process



San Diego Joint Chapters of ACerS & IMAPS

Sponsored by AdTech Ceramics

Thursday, January 23rd, 2020 at 12:00

Evolution of mmWave Semiconductors, Antennae/interfaces, eWLB, to 60GHz BGA devices and more...

Presented by: Vubiq Networks, Mike Pettus, Founder & CTO

Abstract

History review of raw die mmWave ICs to wafer scale BGA, and with some associated packaging and mmWave antennas/interfaces. Further review of flip chip, wire/ribbon bonding, to finally using eWLB packaged devices which enabled an all SMT approach at the system level. Evolution of early integrated antennas to 60 GHz BGA devices. Applications will be shown for point-to-point mmWave links, chipless RFID, and wireless data centers.

Biography

Mr. Pettus obtained his BA in Philosophy, specialization in philosophy of Science and Mathematics, 1972. Self-trained engineer, focus on wireless and millimeter wave. Been working in the wireless high-tech industry for over 40 years. 15 issued patents. Specialization in RF systems engineering, mmWave components/packaging, antenna design. First in the U.S. to obtain frequency-hopping spread-spectrum radio Part 15 certification from the FCC in 1989 while at Metricom. Amateur (“ham”) radio – licensed more than 50 years.

Logistics:

Thursday, January 23rd, 2020 at 12:00 – 1:00 PM. Lunch will be provided.

Location: EMD Performance Materials, @ 6555 Nancy Ridge Drive, Suite #200, San Diego, CA 92123

RSVP required. Space is limited to 30 registrants due to room size; please sign up quickly.

\$20.00 for members. \$25.00 for non-members. \$10 for students with an ID. Please advise if you are non-U.S. citizen when you register. [Register here](#), questions please contact Bill Ishii ----- bill@imaps.org

Thank You very much to our Sponsors for making our technical programming possible!